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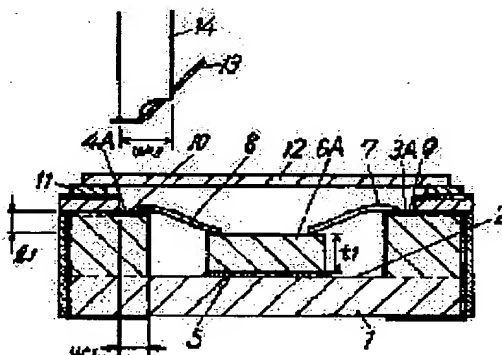
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(54) SAW DEVICE AND MANUFACTURE THEREOF

(57)Abstract:

PURPOSE: To perform miniaturization by providing a level difference part provided on the side wall part of a package above the upper surface of a surface acoustic wave (SAW) chip 6.

CONSTITUTION: This device is provided with the package 1 whose upper surface is open, the SAW chip 6A mounted on the inner bottom surface 2 of the package 1, wires 7 and 8 for connecting an electrode on the upper surface of the SAW chip 6A and the electrodes 9 and 10 on the level difference parts 3A and 4A of the side wall part of the package 1 and a metallic lid 12 mounted to the upper surface opening part of the package 1. Then, the level difference parts 3A and 4A are provided above the upper surface of the SAW chip 6A. Thus, the middle parts of the wires 7 and 8 connecting the electrode on the upper surface of the SAW chip 6A and the electrodes 9 and 10 on the level difference parts 3A and 4A of the package 1 are prevented from projecting to an upper part. Thus, the need of mounting the metallic lid 12 at a higher part so as to prevent contact to the wires 7 and 8 is eliminated and the miniaturization is performed for that portion.



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